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2MBI300VB-060-50

IGBT Modules

Power Module (V series) 600V / 300A / 2-in-1 package

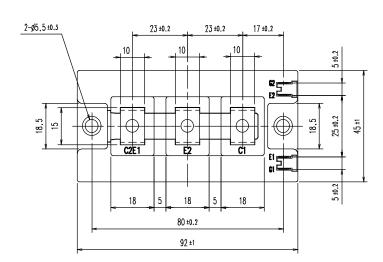
■ Features

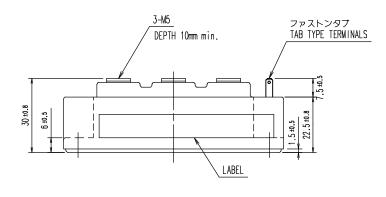
AC-switch High speed switching Voltage drive Low Inductance module structure

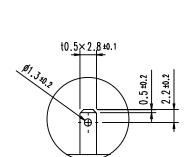
■ Applications

AC-switch for UPS,PCS and etc.

■ Outline drawing (Unit:mm)



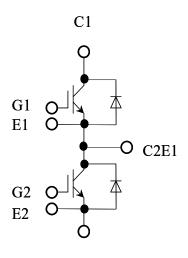




DETAIL TAB TYPE TERMINALS

Weight: 240g (typ.)

■ Equivalent circuit





IGBT Modules

■ Absolute maximum ratings (at T_C= 25°C unless otherwise specified)

	Items	Symbols	Cond	litions	Maximum ratings	Units	
Collector-Emitter voltage		V _{CES}			600	V	
Gate-Emitte	r voltage	V _{GES}			±20	V	
-		1 _C	Continuous	T _C =80°C	300		
Collector cu	rrant	I _C pulse	1ms		600	A	
Collector cu	Helit	-1 _C			300	_ A	
		-I _C pulse	1ms		600		
Collector power dissipation		Pc	1 device		1360	W	
Junction temperature		T _i			175		
Operating junction temperature		τ			150		
(under switching conditions)		T_{jop}			130	°C	
Case temperature		Tc			125		
Storage temperature		$T_{ m stg}$			-40 ~ 125		
Isolation	Between terminal and copper base		AC: 1min		2500	\/AC	
voltage	(*1)	V_{iso}	AC: 1min.		2500	VAC	
Screw	Mounting	-	M5		2.5~3.5	NIm	
torque	Terminals	-	M5		2.5~3.5	N m	

^(*1) All terminals should be connected together during the test.



IGBT Modules

■ Electrical characteristics (at T_i= 25°C unless otherwise specified)

NOTICE:

The external gate resistance (R_g) shown below is one of our recommend value for the purpose of minimum switching loss. However the optimum R_g depends on circuit configuration and/or environment. We recommend that the R_g has to be carefully chosen based on consideration if IGBT module matches design criteria, for example, switching loss, EMC/EMI, spike voltage, surge current and no unexpected oscillation and so on.

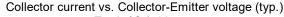
lto	Cympholo	Canditia		Ch	Characteristics		Units
Items	Symbols	Conditions		min.	typ.	max.	
Zero gate voltage collector current	I _{CES}	V _{GE} =0V,V _{CE} =600V		-	-	2.0	mA
Gate-Emitter leakage current	/ _{CFS} V _{CF} =UV, V _{CF} =±2UV		ı	-	400	nA	
Gate-Emitter threshold voltage	$V_{GE(th)}$	V _{CE} =20V,I _C =300mA	V _{CE} =20V,I _C =300mA		6.7	7.2	V
	V _{CE(sat)}		T _j =25°C	-	1.80	2.25	
		$V_{\rm GE}$ =15V, $I_{\rm C}$ =300A	T _j =125°C	-	2.10	-	
Collector-Emitter	(terminal)		T _j =150°C	-	2.30	-	V
saturation voltage	V	T _i =	T _j =25°C	•	1.60	2.05	7 V
	V _{CE(sat)}	$V_{GE} = 15 \text{V}, I_{C} = 300 \text{A}$	T _i =125°C	-	1.90	-	
	(chip)		T _i =150°C		2.00	-	
Internal gate resistance	R _{g(int)}	-		-	3.0	-	Ω
Input capacitance	C ies	V _{CE} =10V, V _{GE} =0V, J	f=1MHz	1	20	-	nF
	t on			-	650	-	
Turn-on time	t _r	V_{CC} =300V, I_{C} =300A, V_{GE} =±15V, R_{g} =4.7 Ω , T_{j} =150°C, L_{s} =30nH - 300 - 600 - 70		-	300	-	nsec
	t _{r(i)}			-	100	-	
Turn-off time	t off			-	7		
rum-on ume	t_{f}			-	70	-	1
	V _F		T _i =25°C	-	1.70	2.15	
		$V_{GE} = 0V, I_{F} = 300A$	T _i =125°C	-	1.60	-	
	(terminal)		T _i =150°C		1.57	-	.,
Forward on voltage	V		<i>T</i> _i =25°C - 1.60	2.05	V		
	V _F	$V_{GE} = 0V, I_{F} = 300A$	T _j =125°C	-	1.50	-	7
	(chip)		T _j =150°C	•	1.47	-	
Reverse recovery time	t _{rr}	I _F =300A		-	200	-	nsec

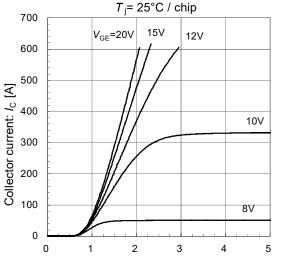
■ Thermal resistance characteristics

Itomo		Conditions	С	Characteristics		
Items	Symbols	Conditions	min.	typ.	max.	- Units
Thermal resistance	D	IGBT	-	-	0.110	
(1device)	R _{th(j-c)}	FWD	-	-	0.180	°C/W
Contact thermal resistance	D	with the sum of some power		0.005		C/VV
(1device) (*1)	R _{th(c-f)}	with thermal compound	-	0.025	-	

^(*1) This is the value which is defined mounting on the additional cooling fin with thermal compound.

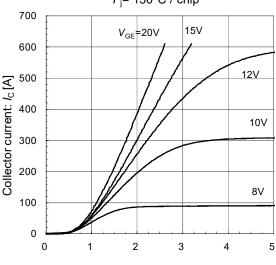
IGBT Modules





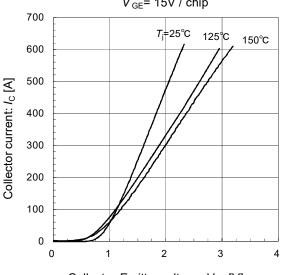
Collector-Emitter voltage: V_{CE} [V]

Collector current vs. Collector-Emitter voltage T_j = 150°C / chip



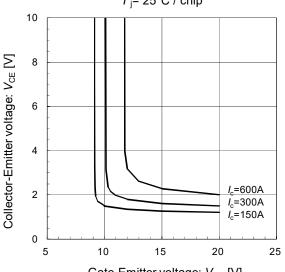
Collector-Emitter voltage: V_{CE} [V]

Collector current vs. Collector-Emitter voltage (typ.) V_{GE} = 15V / chip



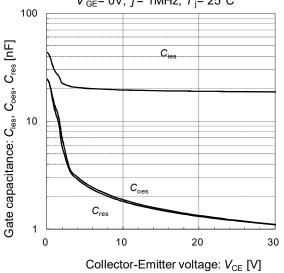
Collector-Emitter voltage: V_{CE} [V]

Collector-Emitter voltage vs. Gate-Emitter voltage (typ.) T_i = 25°C / chip



Gate-Emitter voltage: V_{GE} [V]

Gate capacitance vs. Collector-Emitter Voltage (typ.) V_{GE} = 0V, f= 1MHz, T_i = 25°C

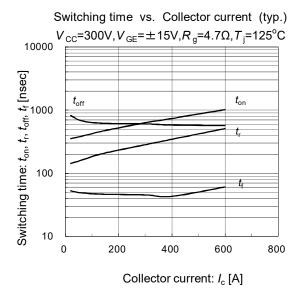


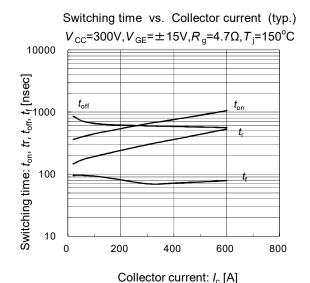
Dynamic gate charge (typ.) $V_{\rm CC}$ =300V, $I_{\rm C}$ =300A, $T_{\rm i}$ =25°C 20 400 15 300 $V_{\rm GE}\left[
ight]$ V_{CE} 10 200 Gate-Emitter voltage: 100 0 -100 -200 -300 -20 400 -1.0 -2.0 0.0 2.0 3.0

Gate charge: Q_g [µC]

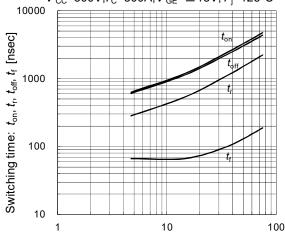
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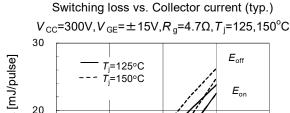
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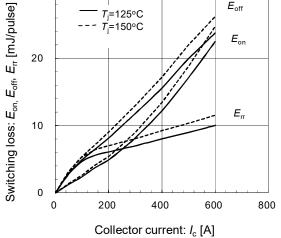




Switching time vs. Gate resistance (typ.) $V_{\rm CC}$ =300V, $I_{\rm C}$ =300A, $V_{\rm GE}$ = \pm 15V, $T_{\rm i}$ =125°C

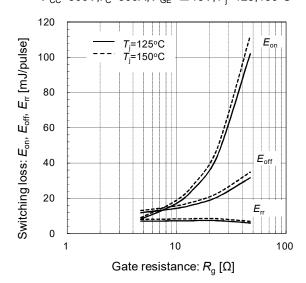




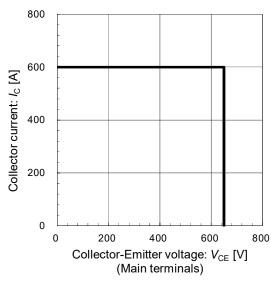


Switching loss vs. Gate resistance (typ.) $V_{\rm CC}$ =300V, $I_{\rm C}$ =300A, $V_{\rm GE}$ =±15V, $T_{\rm i}$ =125,150°C

Gate resistance: R_{α} [Ω]



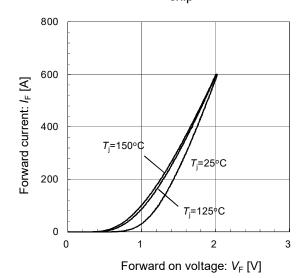
Reverse bias safe operating area (max.) $+V_{GE}=15V$, $-V_{GE}=15V$, $R_{g}=4.7\Omega$, $T_{i}=150^{\circ}$ C



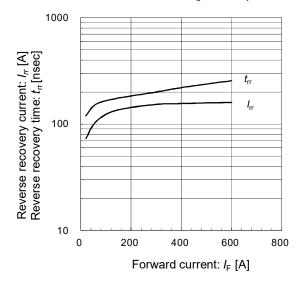


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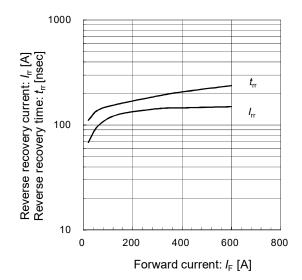
Forward current vs. Forward voltage (typ.) chip



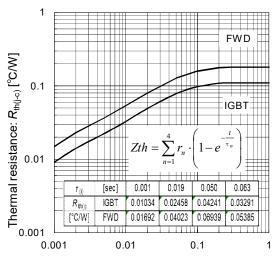
Reverse recovery characteristics (typ.) V_{CC} =300V, V_{GE} =±15V, R_g =4.7 Ω , T_j =150°C



Reverse recovery characteristics (typ.) V_{CC} =300V, V_{GE} =±15V, R_g =4.7 Ω , T_g =125°C



Transient thermal resistance (max.)





IGBT Modules

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